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Texas Instruments SN74LVTH652IPWREP

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### SN74LVTH652-EP 3.3-V ABT OCTAL BUS TRANSCEIVER AND REGISTER WITH 3-STATE OUTPUTS

SCBS776 - NOVEMBER 2003

- Controlled Baseline

   One Assembly/Test Site, One Fabrication Site
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree<sup>†</sup>
- Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V<sub>CC</sub>)
- Supports Unregulated Battery Operation Down To 2.7 V
- Typical V<sub>OLP</sub> (Output Ground Bounce)
   <0.8 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- I<sub>off</sub> and Power-Up 3-State Support Hot Insertion

<sup>†</sup> Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)

CLKAB 1 24 V <sub>CC</sub> SAB 2 23 CLKBA OEAB 3 22 SBA A1 4 21 OEBA A2 5 20 B1 A3 6 19 B2 A4 7 18 B3 A5 8 17 B4 A6 9 16 B5 A7 10 15 B6 A8 11 14 B7 GND 12 13 B8	PW PACKAGE (TOP VIEW)								
	SAB [ OEAB [ A1 [ A2 [ A3 [ A4 [ A5 [ A6 [ A7 ]	3 4 5 7 8 9 10 11	Ο	23 22 21 20 19 18 17 16 15	CLKBA SBA OEBA B1 B2 B3 B4 B5 B6				

### description/ordering information

This bus transceiver and register is designed specifically for low-voltage (3.3-V)  $V_{CC}$  operation, but with the capability to provide a TTL interface to a 5-V system environment.

The SN74LVTH652 consists of bus-transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers.

Output-enable (OEAB and OEBA) inputs are provided to control the transceiver functions. Select-control (SAB and SBA) inputs are provided to select whether real-time or stored data is transferred. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between real-time and stored data. A low input selects real-time data and a high input selects stored data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the SN74LVTH652 device.

T <sub>A</sub>	PACKA	PACKAGE <sup>‡</sup>		TOP-SIDE MARKING	
–40°C to 85°C	TSSOP – PW	Tape and reel	SN74LVTH652IPWREP	LH652EP	

### **ORDERING INFORMATION**

<sup>‡</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.





### SN74LVTH652-EP 3.3-V ABT OCTAL BUS TRANSCEIVER AND REGISTER WITH 3-STATE OUTPUTS SCBS776 - NOVEMBER 2003

### description/ordering information (continued)

Data on the A or B data bus, or both, can be stored in the internal D-type flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) inputs, regardless of the select- or enable-control pins. When SAB and SBA are in the real-time transfer mode, it is possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and OEBA. In this configuration, each output reinforces its input; therefore, when all other data sources to the two sets of bus lines are at high impedance, each set of bus lines remains at its last state.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

When  $V_{CC}$  is between 0 and 1.5 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor and OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

This device is fully specified for hot-insertion applications using  $I_{off}$  and power-up 3-state. The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

						FUNCTION TABLE		
		INPU <sup>-</sup>	TS			DAT	a I/O†	
OEAB	OEBA	CLKAB	CLKBA	SAB	SBA	A1–A8	B1–B8	OPERATION OR FUNCTION
L	Н	H or L	H or L	Х	Х	Input	Input	Isolation
L	Н	$\uparrow$	$\uparrow$	Х	Х	Input	Input	Store A and B data
Х	Н	$\uparrow$	H or L	Х	Х	Input	Unspecified <sup>‡</sup>	Store A, hold B
н	Н	$\uparrow$	$\uparrow$	χ‡	Х	Input	Output	Store A in both registers
L	Х	H or L	$\uparrow$	Х	Х	Unspecified <sup>‡</sup>	Input	Hold A, store B
L	L	$\uparrow$	$\uparrow$	Х	x‡	Output	Input	Store B in both registers
L	L	Х	Х	Х	L	Output	Input	Real-time B data to A bus
L	L	Х	H or L	Х	н	Output	Input	Stored B data to A bus
Н	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus
Н	Н	H or L	Х	Н	Х	Input	Output	Stored A data to B bus
Н	L	H or L	H or L	Н	Н	Output	Output	Stored A data to B bus and stored B data to A bus

<sup>†</sup> The data-output functions can be enabled or disabled by a variety of level combinations at OEAB or OEBA. Data-input functions always are enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.

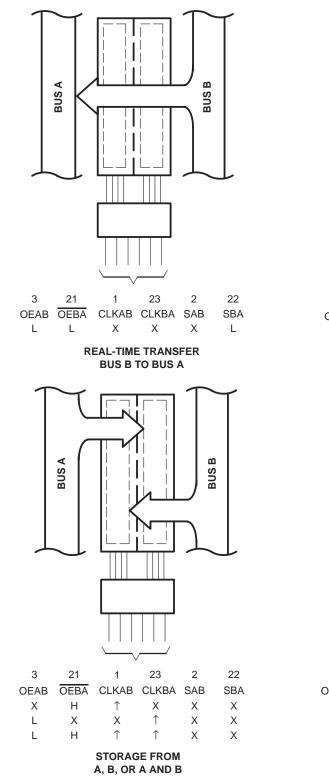
<sup>‡</sup>Select control = L; clocks can occur simultaneously.

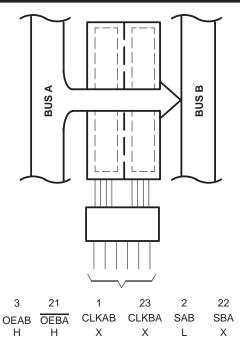
Select control = H; clocks must be staggered to load both registers.



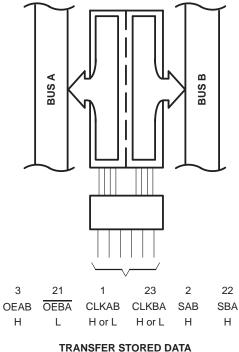


### SN74LVTH652-EP 3.3-V ABT OCTAL BUS TRANSCEIVER AND REGISTER WITH 3-STATE OUTPUTS SCBS776 – NOVEMBER 2003





REAL-TIME TRANSFER BUS A TO BUS B



TO A AND/OR B

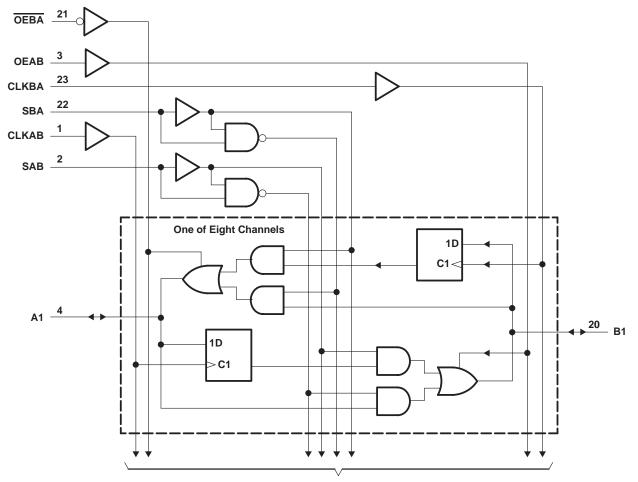






### SN74LVTH652-EP 3.3-V ABT OCTAL BUS TRANSCEIVER AND REGISTER WITH 3-STATE OUTPUTS SCBS776 - NOVEMBER 2003

logic diagram (positive logic)



**To Seven Other Channels** 





### SN74LVTH652-EP 3.3-V ABT OCTAL BUS TRANSCEIVER AND REGISTER WITH 3-STATE OUTPUTS

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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub>	–0.5 V to 4.6 V
Input voltage range, V <sub>I</sub> (see Note 1)	
Voltage range applied to any output in the high-impedance	
or power-off state, V <sub>O</sub> (see Note 1)	
Voltage range applied to any output in the high state, V <sub>O</sub> (see Note 1)	-0.5 V to V <sub>CC</sub> + 0.5 V
Current into any output in the low state, IO	
Current into any output in the high state, I <sub>O</sub> (see Note 2)	64 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	
Package thermal impedance, $\theta_{JA}$ (see Note 3)	
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
  - 2. This current flows only when the output is in the high state and  $V_O > V_{CC}$ .
  - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

### recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
VCC	Supply voltage		2.7	3.6	V
VIH	High-level input voltage		2		V
VIL	Low-level input voltage			0.8	V
VI	Input voltage			5.5	V
IOH	High-level output current			-32	mA
IOL	Low-level output current			64	mA
$\Delta t / \Delta v$	Input transition rise or fall rate	Outputs enabled		10	ns/V
$\Delta t / \Delta V_{CC}$	Power-up ramp rate		200		μs/V
Т <sub>А</sub>	Operating free-air temperature		-40	85	°C

NOTE 4: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.





### SN74LVTH652-EP 3.3-V ABT OCTAL BUS TRANSCEIVER AND REGISTER WITH 3-STATE OUTPUTS SCBS776 - NOVEMBER 2003

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER	TEST CONDITIO	NS	MIN	түр†	MAX	UNIT		
VIK		V <sub>CC</sub> = 2.7 V,	lj = –18 mA			-1.2	V		
		V <sub>CC</sub> = 2.7 V to 3.6 V,	I <sub>OH</sub> = −100 μA	V <sub>CC</sub> -0.2	2				
∨он		V <sub>CC</sub> = 2.7 V,	I <sub>OH</sub> = –8 mA	2.4			V		
		$V_{CC} = 3 V,$	I <sub>OH</sub> = -32 mA	2					
		No. 07.V	I <sub>OL</sub> = 100 μA			0.2			
		$V_{CC} = 2.7 V$	I <sub>OL</sub> = 24 mA			0.5			
V <sub>OL</sub>			I <sub>OL</sub> = 16 mA			0.4	V		
		$V_{CC} = 3 V$	I <sub>OL</sub> = 32 mA			0.5			
			$\begin{array}{c cccc} 2.7 \ V \ to \ 3.6 \ V, & I_{OH} = -100 \ \mu A \\ \hline 2.7 \ V, & I_{OH} = -8 \ mA \\ \hline 3 \ V, & I_{OH} = -32 \ mA \\ \hline I_{OL} = 100 \ \mu A \\ \hline I_{OL} = 24 \ mA \\ \hline I_{OL} = 32 \ mA \\ \hline I_{OL} = 32 \ mA \\ \hline I_{OL} = 64 \ mA \\ \hline 3.6 \ V, & V_I = V_{CC} \ or \ GND \\ \hline 0 \ or \ 3.6 \ V, & V_I = 5.5 \ V \\ \hline 3.6 \ V & V_I = 5.5 \ V \\ \hline V_I = 0 \\ \hline 0, & V_I = V_{CC} \\ \hline V_I = 0 \\ \hline 0, & V_I \ or \ V_O = 0 \ to \ 4.5 \ V \\ \hline V_I = 0 \\ \hline 0, & V_I \ or \ V_O = 0 \ to \ 4.5 \ V \\ \hline V_I = 2 \ V \\ \hline 3.6 \ V & V_I = 0 \ to \ 3.6 \ V \\ \hline 0 \ to \ 1.5 \ V, \ V_O = 0.5 \ to \ 3 \ V, \ OE/\overline{OE} = \ don't \ care \\ \hline 1.5 \ V \ to \ 0, \ V_O = 0.5 \ to \ 3 \ V, \ OE/\overline{OE} = \ don't \ care \\ \hline 3.6 \ V, \ I_O = 0, \ V_I = V_{CC} \ or \ GND \\ \hline Outputs \ high \\ \hline Outputs \ high \\ \hline Outputs \ disabled \\ \hline 3 \ V \ to \ 3.6 \ V, \ One \ input \ at \ V_{CC} \ or \ GND \\ \hline V \ or \ 0 \\ \hline V \ or \ 0 \end{array}$			0.55			
	Constant in suctor	V <sub>CC</sub> = 3.6 V,	$V_I = V_{CC} \text{ or } GND$			±1			
	Control inputs	V <sub>CC</sub> = 0 or 3.6 V,	V <sub>I</sub> = 5.5 V			10			
li –	l <u>i</u>		V <sub>I</sub> = 5.5 V			20	μΑ		
A or B ports‡	V <sub>CC</sub> = 3.6 V	$V_I = V_{CC}$			1				
			$V_{I} = 0$			-5			
loff		$V_{CC} = 0,$	$V_{I} \text{ or } V_{O} = 0 \text{ to } 4.5 \text{ V}$			±100	μΑ		
		No. 2 M	V <sub>I</sub> = 0.8 V	75					
ll(hold)	A or B ports	V <sub>CC</sub> = 3 V	V <sub>I</sub> = 2 V	-75	-75		μA		
. ,		V <sub>CC</sub> = 3.6 V§	-			±500			
IOZPU		$V_{CC} = 0$ to 1.5 V, $V_O = 0.5$ to 3 V, $OE/\overline{OE} = d$	on't care			±100	μΑ		
IOZPD		$V_{CC} = 1.5$ V to 0, $V_O = 0.5$ to 3 V, $OE/\overline{OE} = d$	on't care			±100	μΑ		
			Outputs high			0.19			
ICC		$V_{CC} = 3.6 \text{ V}, I_{O} = 0, V_{I} = V_{CC} \text{ or GND}$	Outputs low			5	mA		
			Outputs disabled			0.19			
∆Icc¶		$V_{CC}$ = 3 V to 3.6 V, One input at $V_{CC}$ – 0.6 V	, Other inputs at V <sub>CC</sub> or GND			0.2	mA		
Ci		$V_{I} = 3 V \text{ or } 0$			4		pF		
Cio		V <sub>O</sub> = 3 V or 0			9		pF		

<sup>†</sup> All typical values are at  $V_{CC}$  = 3.3 V,  $T_A$  = 25°C.

<sup>‡</sup> Unused terminals at V<sub>CC</sub> or GND

§ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another. ¶ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V<sub>CC</sub> or GND.

# timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

			V <sub>CC</sub> = ± 0.1	3.3 V 3 V	V <sub>CC</sub> =	2.7 V	UNIT
			MIN	MAX	MIN	MAX	
fclock	Clock frequency			150		150	MHz
tw	Pulse duration, CLK high or low		3.3		3.3		ns
	Setup time,	Data high	1.2		1.5		
t <sub>su</sub>	A or B before CLKAB <sup>↑</sup> or CLKBA <sup>↑</sup>	Data low	1.6		2.2		ns
t <sub>h</sub>	Hold time, A or B after CLKAB $\uparrow$ or CLKBA $\uparrow$		0.8		0.8		ns





### SN74LVTH652-EP **3.3-V ABT OCTAL BUS TRANSCEIVER AND REGISTER** WITH 3-STATE OUTPUTS SCBS776 - NOVEMBER 2003

switching characteristics over recommended operating free-air temperature range, CL = 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM	TO	V	CC = 3.3 ± 0.3 V	V	V <sub>CC</sub> = 2.7 V		UNIT
	(INPUT)	(OUTPUT)	MIN	түр†	MAX	MIN	MAX	
fmax			150			150		MHz
<sup>t</sup> PLH		A su D	1.8	3.1	4.7		5.6	
<sup>t</sup> PHL	CLKBA or CLKAB	A or B	1.8	3.1	4.7		5.6	ns
<sup>t</sup> PLH	A or D	DerA	1.3	2.3	3.5		4.1	20
<sup>t</sup> PHL	A or B	B or A	1.3	2.4	3.5		4.1	ns
<sup>t</sup> PLH	SBA or SAB‡	A or D	1.5	3.1	4.9		6	20
<sup>t</sup> PHL	SBA OF SAB+	A or B	1.5	3.4	4.9		6	ns
<sup>t</sup> PZH	OEBA	А	1.1	2.9	5.2		6.5	20
<sup>t</sup> PZL	OEBA	A	1.1	3.1	5.2		6.5	ns
<sup>t</sup> PHZ	OEBA		2.3	3.5	5.5		6.1	
<sup>t</sup> PLZ	OEBA	A	2.3	3.7	5.5		5.9	ns
<sup>t</sup> PZH		D	1.3	3	4.7		5.7	20
<sup>t</sup> PZL	OEAB	В	1.3	3.3	4.7		5.7	ns
<sup>t</sup> PHZ	OEAB	В	1.5	3.6	5.6		6.7	20
<sup>t</sup> PLZ	OEAB	В	1.5	3.7	5.6		6.3	ns

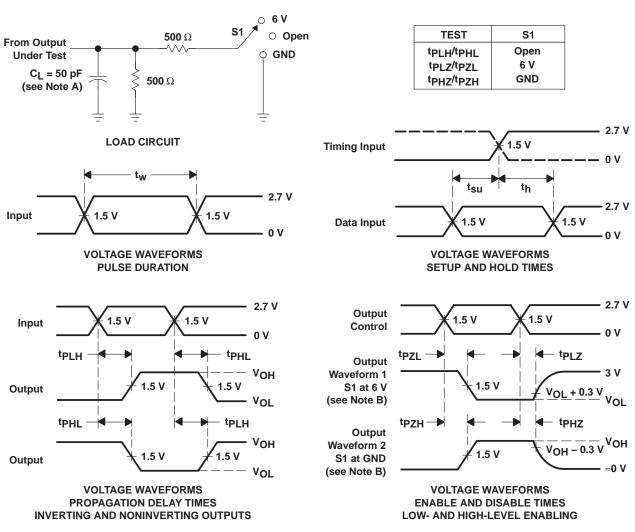
<sup>†</sup> All typical values are at  $V_{CC}$  = 3.3 V,  $T_A$  = 25°C. <sup>‡</sup> These parameters are measured with the internal output state of the storage register opposite that of the bus input.





## SN74LVTH652-EP 3.3-V ABT OCTAL BUS TRANSCEIVER AND REGISTER

WITH 3-STATE OUTPUTS SCBS776 – NOVEMBER 2003



PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
- Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  2.5 ns, t<sub>f</sub>  $\leq$  2.5 ns. D. The outputs are measured one at a time with one transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms







# PACKAGE OPTION ADDENDUM

18-Sep-2008

### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins F	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74LVTH652IPWREP	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/04681-01XE	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. **TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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#### OTHER QUALIFIED VERSIONS OF SN74LVTH652-EP :

Catalog: SN74LVTH652

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

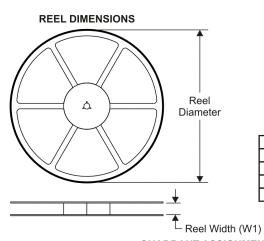


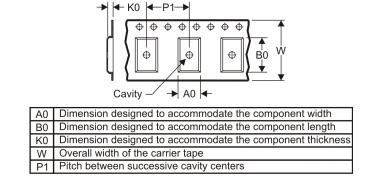


## PACKAGE MATERIALS INFORMATION

26-Jul-2008

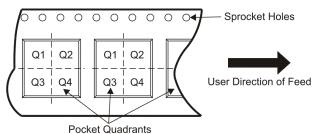
### TAPE AND REEL INFORMATION





TAPE DIMENSIONS

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All	dimensions are	nominal

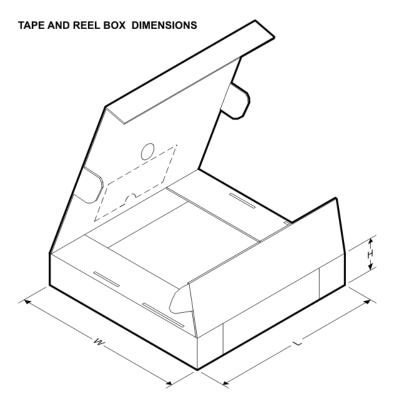
Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVTH652IPWREP	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1





## PACKAGE MATERIALS INFORMATION

26-Jul-2008



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVTH652IPWREP	TSSOP	PW	24	2000	346.0	346.0	33.0



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